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L Number	Hits	Search Text	DB	Time stamp
1	92	assembly and apparatus and solder adj ball near placing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:33
2	4	assembly and apparatus and solder adj ball near placing and hopper and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:29
3	2	assembly and apparatus and solder adj ball near placing and hopper and substrate near stencil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:32
4	2	("4256532"   "5880017").PN.	USPAT	2004/06/15 14:31
5	2	assembly and apparatus and solder adj ball near placing and hopper and substrate near stencil and (438/612; 438/613 ; 438/614 ; 438/615 ; 438/616 ; 257/737 ; 257/738).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:32
6	2	assembly and apparatus and hopper and substrate near stencil and (438/612; 438/613 ; 438/614 ; 438/615 ; 438/616 ; 257/737 ; 257/738).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:33
7	0	assembly and apparatus and hopper and substrate near stencil and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:33
8	247	assembly and apparatus and solder adj ball and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:34
9	0	assembly and apparatus and solder adj ball and 29/\$.cccls. and stencil and hopper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:35
10	1	assembly and apparatus and solder adj ball and 29/\$.cccls. and hopper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:36